

Call for Papers

Special Section on Recent Development of Electro-Mechanical Devices -Selected Papers from International Session on Electro-Mechanical Devices 2008 (IS-EMD2008)-

The Institute of Electronics, Information and Communication Engineers (IEICE) Transactions on Electronics announces forthcoming Special Section on "Recent Development of Electro-Mechanical Devices --- Selected Papers from International Session on Electromechanical Devices 2008 (IS-EMD2008) ---" to be published on **August 2009**.

Recent electronic devices and systems have been making great progress in, for example, digitizing, down-sizing and high signal-rate transmission. For such devices and systems, electro-mechanical devices including electrical contacts as well as electrical and optical signal interconnections are fundamental and critical technical fields and have been continuously improved. Furthermore, in accordance with technical progress from micro-electronics such as MEMS to nano-scale electronics, as well as progress in automotive electronics, fundamental researches and R&D activities in new aspects for these devices and technologies are being intensively conducted. For environment aspects, developments and researches on Pb-free and Cd-free contact and interconnection materials have been strongly required. Recycle, reuse, and reduce techniques are also important issues for electro-mechanical devices.

Under these circumstances, in order to stimulate R&D activities on the EMD fields, the Technical Committee of EMD held the first International Session on EMD in 2001, and issued the Special Section in the IEICE Transactions. The 8th International Session on EMD (IS-EMD2008) will be held in Sendai on November 2008.

For this Special Section on IS-EMD2008, not only those who will present their works in IS-EMD2008 but all other authors in this field are invited to submit their papers.

The topics of interests include the followings, but not limited to:

★**Electro-Mechanical Devices & Components**

-Micro Electromechanical Systems, Relay & Switch, Electrical & Optical Connector, Human Interface Devices, Electromechanical Transducers and Sensors, Actuator & Small Motor, Arrester & Fuse.

★**Materials**

-Contact, Spring, Molding, and Other Materials Related to the Electromechanical Devices.

★**Technologies**

-Electrical Contact, Arc Discharge Phenomena, Tribology, Connection & Inter-connection, Plating, Molding, Metal Machining, Device Mounting & Packaging, Board & Substrate, Optoelectronics, Packaging, and Other Related Technologies.

★**Applications**

-Compatible Design with Environment, Pb-Free and Cd-Free Technologies, Recycle Re-use, and Reduce Technologies.

[Submission Instructions]

The deadline for submission is **December 12, 2008**. This special section will accept only papers submitted through electronic submission procedure. Prospective authors are requested to follow carefully the submission process described below.

- (1) Submit a paper using the IEICE Web site https://review.ieice.org/regist_e.aspx. Authors should choose the "[*Special-EC*] *Recent Development of Electro-Mechanical Devices (IS-EMD2008)*" as a "Type of Issue (Section)/Category of Transactions" on the online screen. Do not choose "[*Regular-EC*]".
- (2) Send "One copy of the printed manuscript including figures and tables", "Copyright Transfer and Page Charge Agreement" and "Confirmation Sheet of Manuscript Registration" to

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by postal mail (NOT by FAX or E-mail). Please do not forget to send "Copyright Transfer and Page Charge Agreement" and "Confirmation Sheet of Manuscript Registration". We cannot start the review process without them, even if we receive the manuscript.

*Manuscript should be prepared according to the guideline in the "Information for Authors". The latest version of it is available at the following web site; http://www.ieice.org/eng/shiori/mokuji_es.html.

*At least one of the authors must be an IEICE member when the manuscript is submitted for review.

*The length of a full paper should not exceed eight printed pages, and of a letter should not exceed two pages.

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* Please note that if accepted, all authors, including authors of invited papers, should pay for the page charge covering partial cost of publication. Authors will receive 50 copies of the reprint.